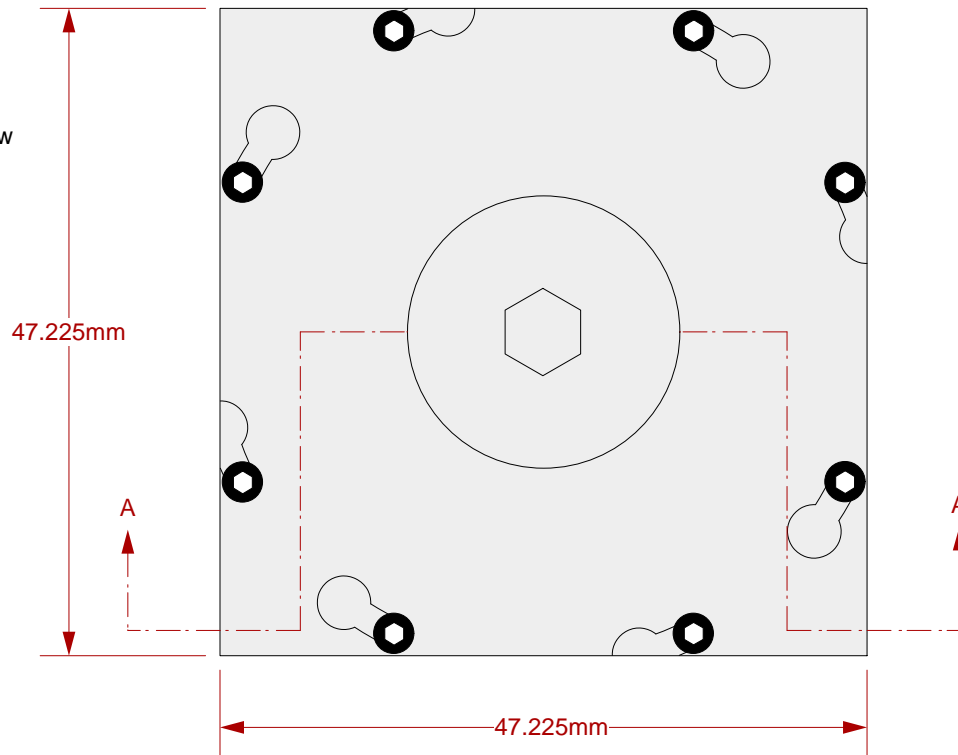


GHz BGA Socket - Direct mount, solderless

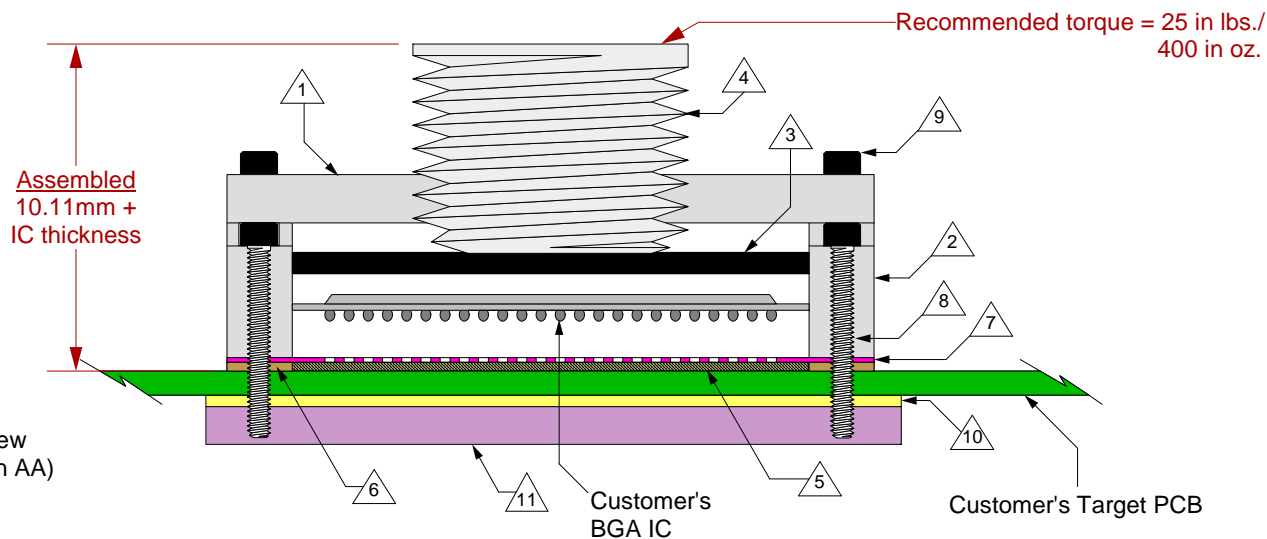
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 4.0mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Cirlex or equivalent.
Thickness = 0.75mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation Plate: FR4/G10, Thickness = 1.59mm. |
| 11 | Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm. |

SG-BGA-6053 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: F

Drawing: H. Hansen

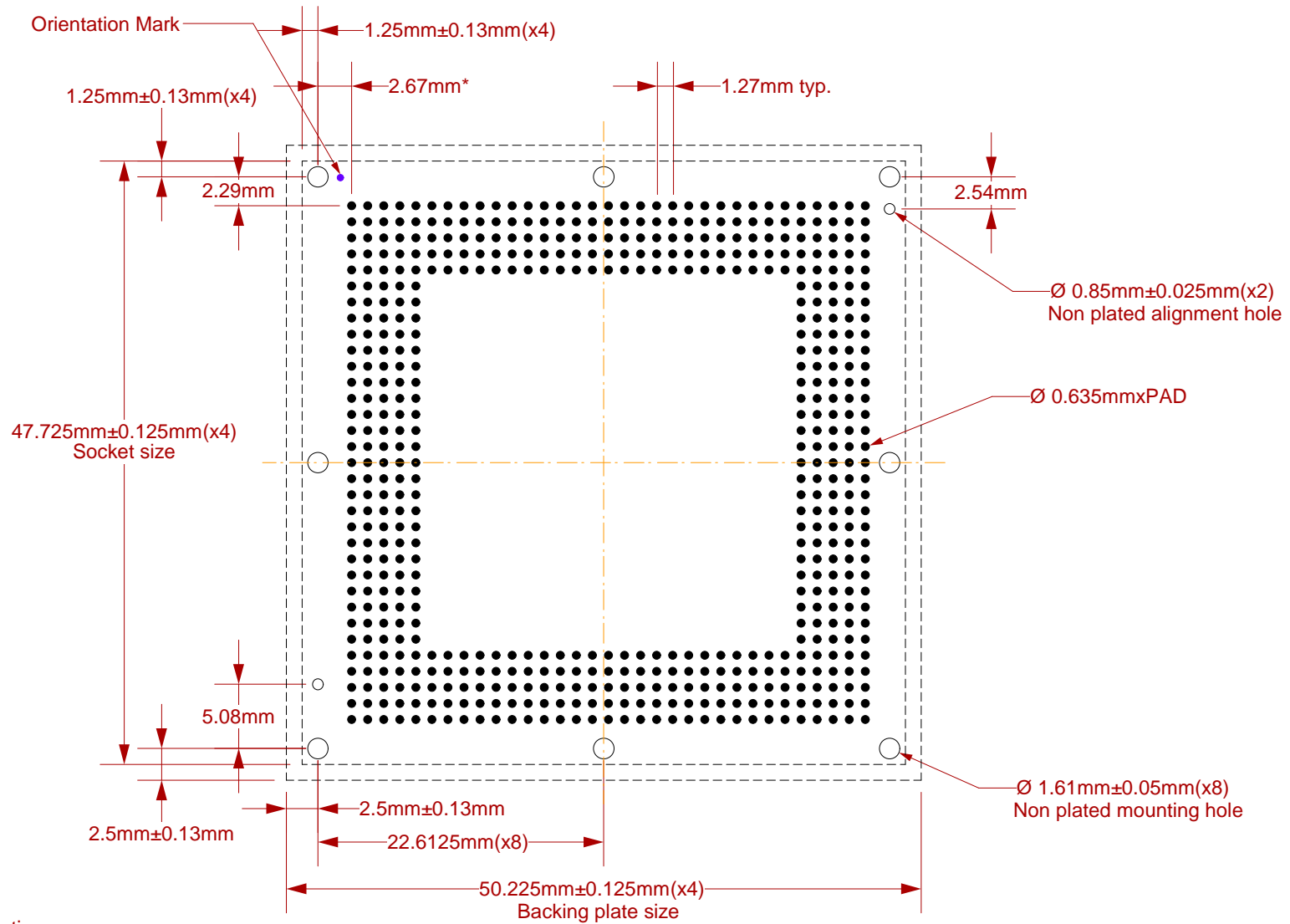
Date: 7/10/02

File: SG-BGA-6053 Dwg

Modified: 7/17/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




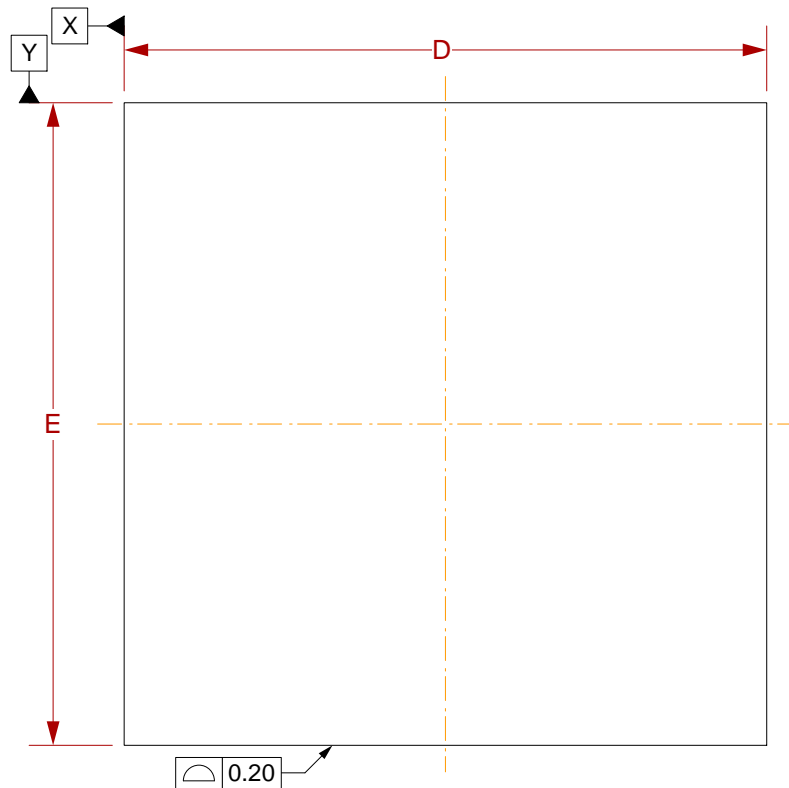
Target PCB Recommendations

Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

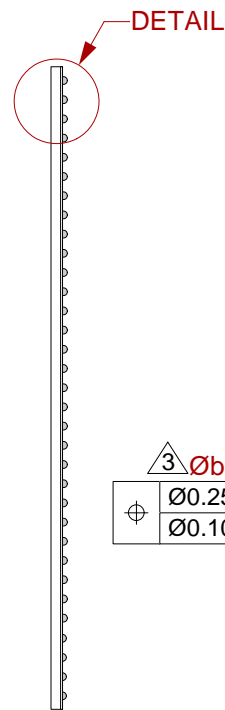
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

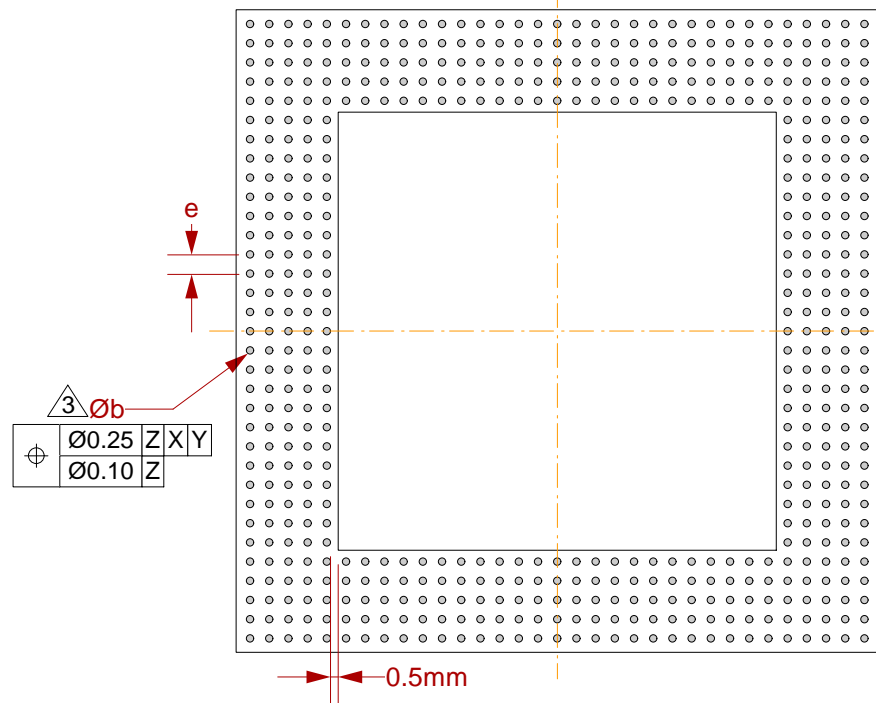
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-6053 Drawing</p>		Status: Released	Scale: 2:1	Rev: F
	<p>Drawing: H. Hansen</p>		<p>Date: 7/10/02</p>		
	<p>File: SG-BGA-6053 Dwg</p>		<p>Modified: 7/17/09, AE</p>		



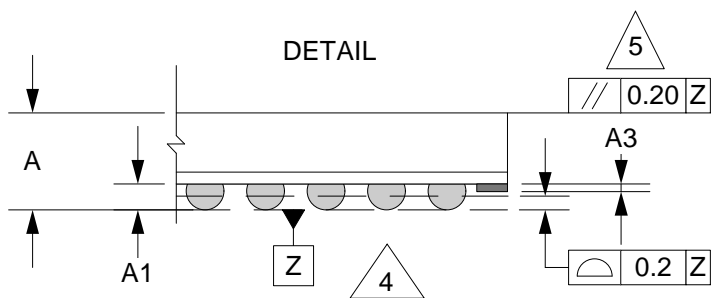
TOP VIEW



SIDE VIEW



BOTTOM VIEW



1. Dimensions are in millimeters.

2. Interpret dimensions and tolerances per ASME Y14.5M-1994.


3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

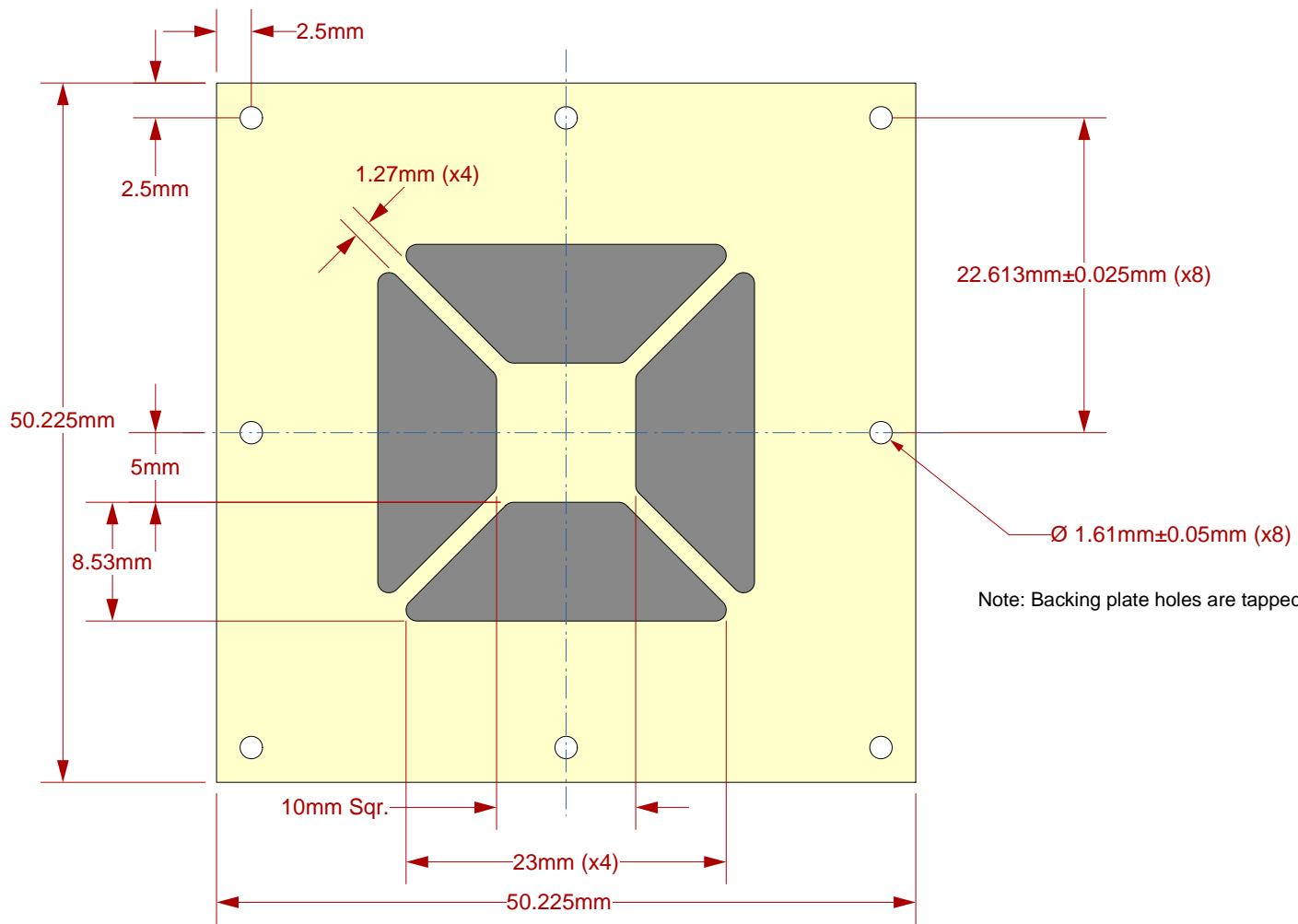
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.5	0.7
A3	0.2mm	
b		0.90
D	42.50 BSC	
E	42.50 BSC	
e	1.27 BSC	

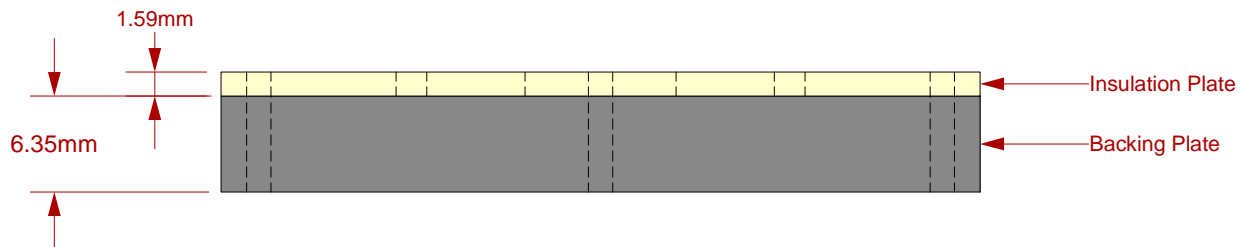
Array: 33x33

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	<p>Drawing: H. Hansen</p>	<p>Date: 7/10/02</p>		
	<p>File: SG-BGA-6053 Dwg</p>	<p>Modified: 7/17/09, AE</p>		


Top View



Side View



Description: Insulation Plate and Backing Plate

SG-BGA-6053 Drawing		Status: Released	Scale: -	Rev: F
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	File: SG-BGA-6053 Dwg		Modified: 7/17/09, AE	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)